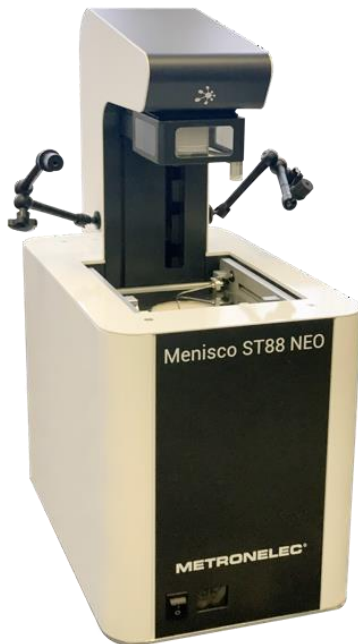


Wetting Balance – Solderability Tester: **MENISCO ST88 NEO**



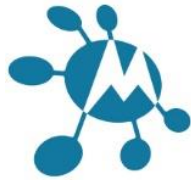
Our Solderability Test Systems are designed to provide fast, accurate and objective measurement of solderability for components, including SMD and printed circuit boards.

The system's output results are expressed in quantitative units – capillary wetting forces (mN) and wetting meniscus angle (degrees).

The results directly correspond to the solder wettability of the specimen.

The Metronelec solderability systems advance the state of the art of solderability testing by eliminating the need to use indirect comparisons or subjective operator interpretations.

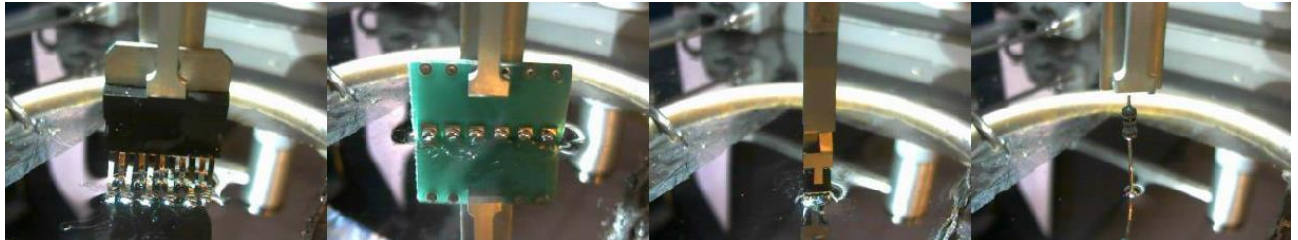
	SPECIFICATIONS
Dipping speed	0,1-50mm/s by step of 0,1 mm/s
Immersion depth	0.01-15mm by step of 0.01 mm
Dwell time	3 to 120 s (more on demand)
Max. net component weight	35 g
Solder bath diameter	80 mm
Solder bath capacity	2 kg
Globule size (mm)	1, 2, 3.2 and 4mm
Temperature setting range	0-450°C
Temperature controlling accuracy	+ /- 1 ° (standard request 3°C)
Weight sensor type	LVDT
Force measurement accuracy	0.001 mN
Force measurement range	0.1 mN to 40 mN
Position sensor type	Hall effect
Stroke: Z-axis accuracy	0.01 mm
Operation software	Windows 10
Data output format	Graph expressed in force or angle, table of values from clipboard or ASCII from file, report with pass/fail, video, picture.
Graph with curve	Yes
SPC monitor	Yes
Data shown with "pass and reject" after each test	Yes
Programmable of test parameter by PC	Yes
Maximum storage of tested data	No limit
Maximum test program available	No limit
Test cycle time (0402 passive)	60 s
Closed loop control (motor)	Yes
Video capture	Yes
Machine dimensions (Without packaging)	310 width x 500 large x 720 height
Electrical input	110-220vac, 50/60Hz @5amp
Nitrogen input	4-6 bar, 4-6 mm tube
Net machine weight	40 kg
Language	Chinese, English, French and German



Solder bath module

Test of conventional components. Test of PCB coupons. Measure of flux / alloy characteristics. Dip and look tests.

Bath method



Multi leads device

IPC coupon test

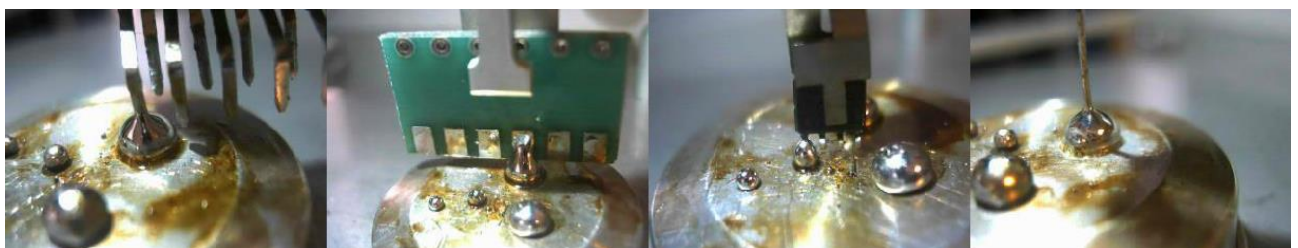
SO8

TH resistor

Globules module

Including the four sizes 1, 2, 3.2 and 4 mm on the same module. Motorized table in X and Y. No need to wait for the temperature when you swap. Test of SMD's and small components
 Test of PCB coupons.

Globule method

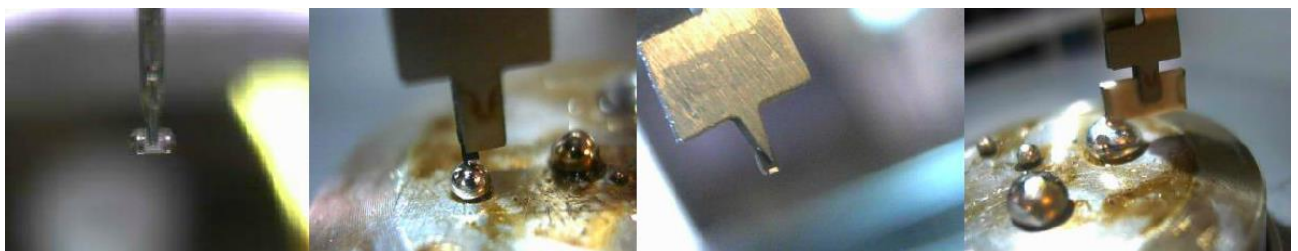


Multi leads device(3.2)

IPC coupon test

SO8 (2)

TH resistor



0201 chip

1 mm globule

0.5 x 0.9 x 0.4 mm

1806 chip

Meets requirement of all international standards:

- IPC/EIA J-STD 002 1 003
- JEDEC MIL 883 L
- IEC 68-2-69; IEC 68-2-58
- NFC 89-400
- Other standard user definitions

